

Customer No.: 31561  
Application No.: 10/709,179  
Docket No.: 10544-US-PA

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Examiner: HA, NATHAN W.

Group Art Unit: 2814

In re PATENT APPLICATION of

Applicants : Chang et al.

Serial No. : 10/709,179

Filed : April 19, 2004

For : STACK-TYPE MULTI-CHIP  
PACKAGE AND METHOD OF  
FABRICATING BUMPS ON  
THE BACKSIDE OF A CHIP

**AMENDMENTS**

DO NOT ENTER.

N.H.

8/16/08

) Attorney Docket: 10544-US-PA  
) \_\_\_\_\_

**The Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10544-US-PA)**

**AMENDMENTS AND RESPONSE TO OFFICE ACTION**

United States Patent and Trademark Office  
Customer Service Window  
Mail Stop **AF**  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

Dear Sir:

The Office Action dated June 06, 2008, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.